

Q2170A Automatic Wire Bonder

Designed for Complex Hybrid, Opto-Electronic and I.C. Assembly Requirements

Specifications*

Standard Features – Hardware

30° Rotary Bond Head
On Axis Linear Theta Encoder
4" X 3.65" table travel
Brushless Motors with Smart Feedback
4 Channel Ultrasonic Generator (60 KHz)
Solid State Vision System
Matrox Pattern Recognition System
Flat Panel Monitor
Stereo Zoom 4 Microscope
Wireless Mouse
Galil Motion Control System
Windows™ XP OS
Fiber Optic Light Source

Standard Features – Software

Point and Click Bond Targeting
Simple, Intuitive Programming
Easy Bond Process Editing
Extensive Program Storage
Bond Parameter Library
Unlimited Wire Program Storage
Multiple Stitch Bonding
Program Wire Groups for Multi Device,
High Wire Count Hybrids
Custom Wire Profiles Available for
Unique Applications

Specifications

Aluminum/Gold Wire

Size Range
0.0007" – 0.003" (17.8 – 76.2 microns)
Maximum Wires Per Device
Unlimited
Spool Diameter
.5" or 2.0" (12.7 or 50.8mm)
Wire Feed Angle
30°, 45°, or 60°

Bonding Speed per Wire

30° Standard Bond Head
490 – 550 ms

XY Table

Resolution
 $\pm 0.0000625"$ (± 1.6 microns)
Bonding Pitch
0.00275" (69.9 microns)

Options and Accessories

Options

Programmable Temperature Controller(s)
Deep Access 60°
Programmable U/S Generator
High Frequency U/S Generator / Transducer
Large Table Travel (Up to 12" x 12")

Accessories

Manual Workholder
Heated Manual Workholder
Ethernet Adapter for Networking Bonders
Additional Fiber Optic Light Source

Miscellaneous

Remote Diagnostics Capability
CE Mark

Facilities

Electric 120 VAC, 50/60 Hz, 20A
N2 or clean, dry air
Vacuum / Air as required for workholder

Dimension/Weight

Height: 72" (182.88 cm)
Width: 39" (99.09 cm)
Depth: 37" (93.98 cm)
Table Height: 40" (101.60 cm)
Weight: 600 pounds (273 Kg)
Crated Weight: 750 pounds (341 Kg)

* Subject to Change

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